

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









N-Channel Power MOSFET

100V, 70A, 13mΩ

FEATURES

- Low R_{DS(ON)} to minimize conductive loss
- Low gate charge for fast power switching
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

ΔD	DI	IC	ΔΤΙ	ION

- Synchronous Rectifier in SMPS
- LED lighting application
- 48V Battery System

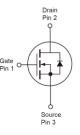
KEY PERFORMANCE PARAMETERS				
PARAMETER VALUE UI				
V_{DS}	100	٧		
R _{DS(on)} (max)	13	mΩ		
$\overline{Q_g}$	145	nC		











Notes: MSL 3 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RAT	TINGS (T _A = 25°C	C unless otherwise no	oted)	
PARAMETER		SYMBOL	Limit	UNIT
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	±20	V
	T _C = 25°C		70	
Continuous Drain Current (Note 3)	$T_C = 70$ °C		61	
	$T_A = 25^{\circ}C$	I _D	12	— A
	T _A = 70°C		9	
Drain Current-Pulsed (Note 1)		I _{DM}	150	А
Avalanche Current, L=0.5mH		I _{AS} , I _{AR}	25	А
Avalanche Energy, L=0.5mH		E _{AS} , E _{AR}	156	mJ
	$T_C = 25^{\circ}C$		120	
Maximum Power Dissipation (Note 2)	$T_C = 70$ °C		80	14/
	T _A = 25°C	I _D	8.3	W
	T _A = 70°C		5.3	
Storage Temperature Range		T _{STG}	- 55 to +150	°C
Operating Junction Temperature Range		TJ	- 55 to +150	°C



THERMAL PERFORMANCE				
PARAMETER	SYMBOL	Limit	UNIT	
Thermal Resistance – Junction to Case	R _{eJC}	1	°C/W	
Thermal Resistance – Junction to Ambient	$R_{\Theta JA}$	40	°C/W	

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static	Static					
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV _{DSS}	100			V
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 30A$	R _{DS(ON)}		10	13	mΩ
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	$V_{GS(TH)}$	2	3	4	V
Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	I _{DSS}			1	μΑ
Gate Body Leakage	$V_{GS} = \pm 20V, V_{DS} = 0V$	I _{GSS}			±100	nA
Dynamic		•				
Total Gate Charge	$V_{DS} = 50V, I_D = 30A,$	Q_g		145		
Gate-Source Charge		Q_{gs}		25		nC
Gate-Drain Charge	$V_{GS} = 10V$	Q_{gd}		43		
Input Capacitance		C _{iss}		4300		_
Output Capacitance	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1.0MHz	C _{oss}		300		pF
Reverse Transfer Capacitance	1 = 1.0IVIM2	C _{rss}		120		
Switching		•				
Turn-On Delay Time		t _{d(on)}		27		
Turn-On Rise Time	$V_{GS} = 10V, V_{DS} = 50V,$	t _r		13		
Turn-Off Delay Time	$R_G = 3\Omega$,	t _{d(off)}		15		ns
Turn-Off Fall Time		t _f		42		
Source-Drain Diode						
Forward On Voltage	$V_{GS} = 0V, I_{S} = 30A$	V _{SD}		0.8	1.3	V
Reverse Recovery Time	I _S = 30A, T _J = 25°C	t _{rr}		165		ns
Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	Q _{rr}		175		nC

Notes:

- 1. Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$
- 2. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design. $R_{\theta JA}$ shown below for single device operation on FR-4PCB in still air.
- 3. The maximum current is limited by package.



TSM70N10
Taiwan Semiconductor

ORDERING INFORMATION

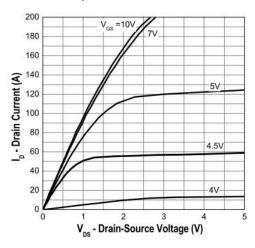
PART NO.	PACKAGE	PACKING	
TSM70N10CP ROG	TO-252 (DPAK)	2,500pcs / 13" Reel	
TSM70N10CH C5G	TO-251 (IPAK)	75pcs / Tube	
TSM70N10CH X0G	TO-251S (IPAK SL)	75pcs / Tube	



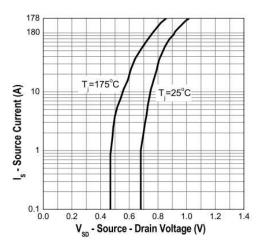
CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

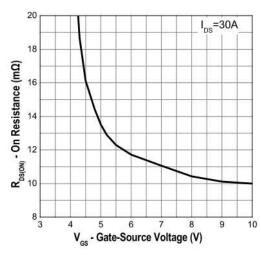
Output Characteristics



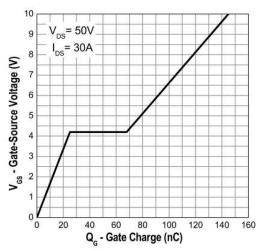
Transfer Characteristics



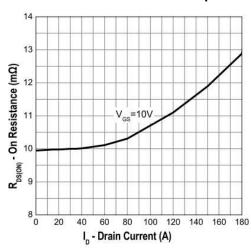
On-Resistance vs. Gate-Source Voltage



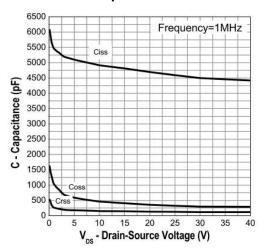
Gate Charge



On-Resistance vs. Junction Temperature



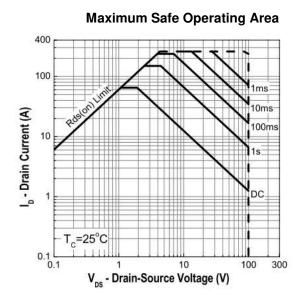
Capacitance

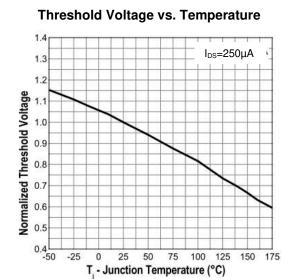




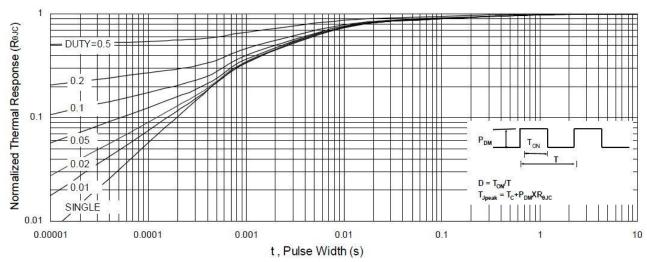
CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)





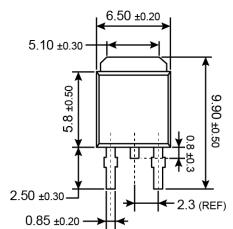
Normalized Thermal Transient Impedance, Junction-to-Ambient

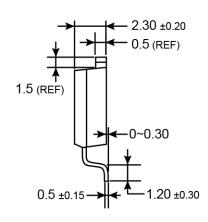




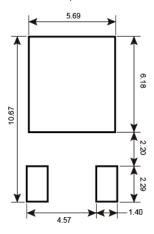
PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

TO-252

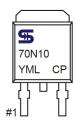




SUGGESTED PAD LAYOUT (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

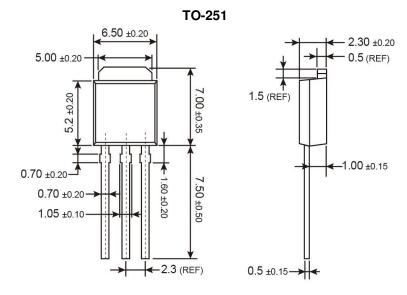
O =Jan P =Feb Q =Mar R =Apr

S =May T =Jun U =Jul V =Aug W =Sep X =Oct Y =Nov Z =Dec

L = Lot Code $(1\sim9, A\sim Z)$



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

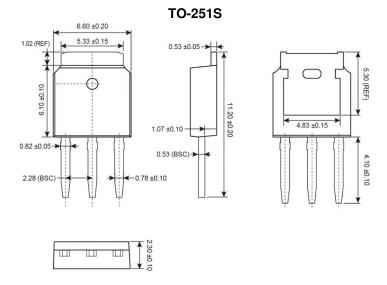
 $oldsymbol{O}$ =Jan $oldsymbol{P}$ =Feb $oldsymbol{Q}$ =Mar $oldsymbol{R}$ =Apr $oldsymbol{S}$ =May $oldsymbol{T}$ =Jun $oldsymbol{U}$ =Jul $oldsymbol{V}$ =Aug

W = Sep X = Oct Y = Nov Z = Dec

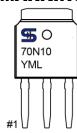
L = Lot Code (1~9, A~Z)



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)



MARKING DIAGRAM



Y = Year Code

M = Month Code for Halogen Free Product

O =Jan P =Feb

Q =Mar **R** =Apr

S = May T = Jun

U =Jul **V** =Aug

W =Sep X =Oct

Y =Nov Z =Dec

L = Lot Code $(1\sim9, A\sim Z)$



Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.